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(54) Title: APPARATUS AND METHOD FOR SEPARATING WAFER SLICES

(57) Abstract: An apparatus to separate a wafer from a pre-sliced boule of wafers may include a conveyor configured to move the pre-sliced boule of wafers from a first end to a second end. A lift yoke, positioned proximate the second end, may include a wafer slot configured to receive a first wafer of the pre-sliced boule therein when the pre-sliced boule is positioned at the second end. A pusher blade may be configured to raise the lift yoke along with the first wafer positioned in its wafer slot from a first position to a second position. The wafer slot may be vertically aligned with the conveyor at the first position and the wafer slot may be positioned above the conveyor in the second position.



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